

Layer Stack Up Detail for: PMP6659B_.PcbDoc			
Layer Name	Drill Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	2.8mil	FR-4 Tg High
Bottom Layer	(.GBL)	2.8mil	
Bottom Solder Mask	(.GBS)		Solder Resist

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
3600MIL X 3700MIL

Number of Layers : 2
 MIN. TRACK WIDTH: 10 MIL
 MIN. CLEARANCE: 10 MIL
 MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2ML) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:

FR-4 FR-4 High Tg OTHER
 THICKNESS: 62 MIL (1.6mm) +/-10% OTHER
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/-
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/-

COPPER THICKNESS (FINISHED):

OUTER: 1.4MIL (1oz) 2ML (1.4oz) 2.8MIL (2oz)
 INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz) N/A

DRILLING:

REFERENCE: AS SHOWN NC_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER

BOARD FINISH:

SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER
 SOLDER RESIST COLOR: GREEN BLUE OTHER

SURFACE FINISH:

IMMERSION GOLD (ENIG)
 1MIL TIN/SILVER OR EQUIV OTHER

ARRAY/PANEL:

CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S ID/LOGO: RAL METAL SILK



PROJECT TITLE:
PMP6659B

DESIGNED FOR:
Public Release

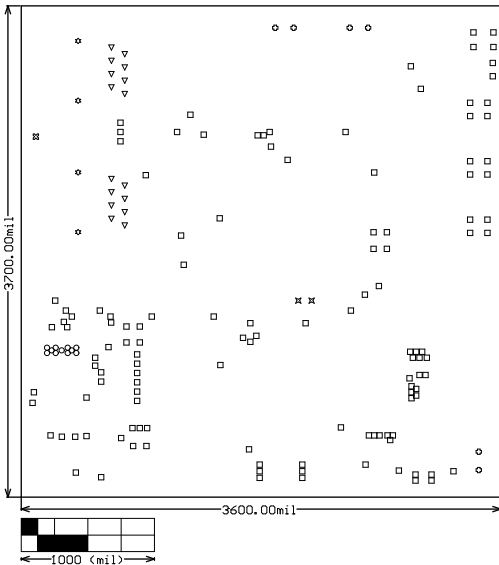
FILE NAME:
PMP6659B_.PcbDoc

ENGINEER:
Ajinder Singh

LAYOUT BY:
Kryton-Solutions/JT

SCALE: 1.00

ALTIM DESIGNER VERSION:
10.0.0.27009



Symbol	Hit Count	Tool Size	Plated	Hole Type
o	11	10mil (0.254mm)	PTH	Round
□	126	12mil (0.305mm)	PTH	Round
▽	16	35mil (0.889mm)	PTH	Round
x	2	38mil (0.965mm)	PTH	Round
o	6	50mil (1.27mm)	PTH	Round
⊗	1	63mil (1.6mm)	PTH	Round
⊙	4	128mil (3.251mm)	NPTH	Round
	166 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6659	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Fabrication Drawings	GENERATED : 1/9/2014 4:12:56 PM		
PLOT NAME = Fabrication Drawing	TEXAS INSTRUMENTS		

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